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(FILE 'HOME' ENTERED AT 12:07:28 ON 15 OCT 2004)

FILE 'BIOSIS, CAPLUS, EMBASE, MEDLINE, CANCERLIT, JAPIO' ENTERED AT
12:07:48 ON 15 OCT 2004

L1	4 S (PASSIVATION MONOLAYER)
L2	4 DUPLICATE REMOVE L1 (0 DUPLICATES REMOVED)
L3	1 S L2 AND ELECTRODE?
L4	10730 S (SELF ASSEMBLED MONOLAYER?)
L5	1 S L4 AND (PASSIVATION AGENT)
L6	0 S (PAASIVATION AGENT)
L7	193 S (PASSIVATION AGENT)
L8	5 S L7 AND MONOLAYER?
L9	5 DUPLICATE REMOVE L8 (0 DUPLICATES REMOVED)
L10	2 S L9 AND ELECTRODE?

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L8	5 S L7 AND MONOLAYER?
L9	5 DUPLICATE REMOVE L8 (0 DUPLICATES REMOVED)
L10	2 S L9 AND ELECTRODE?

ANSWER 3 OF 4 CAPLUS COPYRIGHT 2004 ACS on STN

AN 1996:326332 CAPLUS
DN 125:178469
ED Entered STN: 05 Jun 1996
TI Nanocrystal gold molecules
AU Whetten, Robert L.; Khoury, Joseph T.; Alvarez, Marcos M.; Murthy, Srihari; Vezmar, Igor; Wang, Z. L.; Stephens, Peter W.; Cleveland, Charles L.; Luedtke, W. D.; Landman, Uzi
CS Sch. Phys. Chem., Georgia Inst. Technol., Atlanta, GA, 30332, USA
SO Advanced Materials (Weinheim, Germany) (1996), 8(5), 428-33
CODEN: ADVMEW; ISSN: 0935-9648
PB VCH
DT Journal
LA English
CC 66-5 (Surface Chemistry and Colloids)
Section cross-reference(s): 65, 75
AB Au nanocrystals passivated by self-assembled monolayers of straight-chain alkylthiolate mols. were obtained as highly purified mol. materials of high intrinsic stability. Evidence is presented for a predicted discrete sequence of energetically optimal face centered cubic structures of a truncated octahedral morphol. motif. The nanocrystal materials have a propensity to form extended superlattices.
ST gold nanocrystal **passivation monolayer** property; thiol surfactant passivated monolayer gold; morphol gold nanocrystal passivated monolayer; structure gold nanocrystal passivated monolayer
IT Surfactants
(gold nanocrystals passivated by self-assembled Dodecanethiol monolayers)
IT Mass spectra
Surface structure
(of gold nanocrystals passivated by self-assembled monolayers of straight-chain alkylthiolates)
IT Crystallites
(nanocrystals, of gold passivated by self-assembled monolayers of straight-chain alkylthiolates)
IT 112-55-0, 1-Dodecanethiol
RL: MOA (Modifier or additive use); PEP (Physical, engineering or chemical process); PROC (Process); USES (Uses)
(gold nanocrystals passivated by self-assembled monolayers of)
IT 7440-57-5, Gold, properties
RL: PEP (Physical, engineering or chemical process); PRP (Properties); PROC (Process)
(nanocrystals passivated by self-assembled monolayers and properties of)

ANSWER 3 OF 4 CAPLUS COPYRIGHT 2004 ACS on STN

AN 1996:326332 CAPLUS
DN 125:178469
ED Entered STN: 05 Jun 1996
TI Nanocrystal gold molecules
AU Whetten, Robert L.; Khoury, Joseph T.; Alvarez, Marcos M.; Murthy, Srihari; Vezmar, Igor; Wang, Z. L.; Stephens, Peter W.; Cleveland, Charles L.; Luedtke, W. D.; Landman, Uzi
CS Sch. Phys. Chem., Georgia Inst. Technol., Atlanta, GA, 30332, USA
SO Advanced Materials (Weinheim, Germany) (1996), 8(5), 428-33
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DT Journal
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ST gold nanocrystal **passivation monolayer** property; thiol surfactant passivated monolayer gold; morphol gold nanocrystal passivated monolayer; structure gold nanocrystal passivated monolayer
IT Surfactants
(gold nanocrystals passivated by self-assembled Dodecanethiol monolayers)
IT Mass spectra
Surface structure
(of gold nanocrystals passivated by self-assembled monolayers of straight-chain alkylthiolates)
IT Crystallites
(nanocrystals, of gold passivated by self-assembled monolayers of straight-chain alkylthiolates)
IT 112-55-0, 1-Dodecanethiol
RL: MOA (Modifier or additive use); PEP (Physical, engineering or chemical process); PROC (Process); USES (Uses)
(gold nanocrystals passivated by self-assembled monolayers of)
IT 7440-57-5, Gold, properties
RL: PEP (Physical, engineering or chemical process); PRP (Properties); PROC (Process)
(nanocrystals passivated by self-assembled monolayers and properties of)

AN 1999:16013 CAPLUS

DN 130:144567

ED Entered STN: 12 Jan 1999

TI Alkyl-terminated Si(111) surfaces: A high-resolution, core level photoelectron spectroscopy study

AU Terry, Jeff; Linford, Matthew R.; Wigren, Christer; Cao, Renyu; Pianetta, Piero; Chidsey, Christopher E. D.

CS Stanford University, Stanford, CA, 94309, USA

SO Journal of Applied Physics (1999), 85(1), 213-221

CODEN: JAPIAU; ISSN: 0021-8979

PB American Institute of Physics

DT Journal

LA English

CC 66-4 (Surface Chemistry and Colloids)

Section cross-reference(s): 22, 73

AB The bonding of alkyl monolayers to Si(111) surfaces has been studied with high-resolution core level photoelectron spectroscopy (PES). Two very different wet-chemical methods have been used to prepare the alkyl monolayers: (i) Olefin insertion into the H-Si bond of the H-Si(111) surface, and (ii) replacement of Cl on the Cl-Si(111) surface by an alkyl group from an alkyllithium reagent. In both cases, PES has revealed a C 1s component shifted to lower binding energy and a Si 2p component shifted to higher binding energy. Both components are attributed to the presence of a C-Si bond at the interface. Along with photoelectron diffraction data [Appl. Phys. Lett. 71, 1056, (1997)], these data are used to show that these two synthetic methods can be used to functionalize the Si(111) surface.

ST alkyl terminated silicon surface photoelectron spectroscopy; passivation chlorine hydrogen terminated silicon

IT Annealing

(annealing alkyl monolayers to Si(111) surfaces studied with high-resolution core level photoelectron spectroscopy)

IT Adsorbed monolayers

Alkyl groups

Chemical chains

(bonding of alkyl monolayers to Si(111) surfaces studied with high-resolution core level photoelectron spectroscopy)

IT Passivation

(novel alkyl **passivation monolayers** on Si(111))

surfaces studied with high-resolution core level photoelectron spectroscopy)

IT 2229-07-4D, Methyl, reaction production with Si surface 2492-36-6D, Butyl, reaction production with Si surface 2672-01-7D, Pentyl, reaction production

with Si surface 34448-85-6D, Octadecyl, reaction production with Si surface 49765-51-7D, Decyl, reaction production with Si surface

RL: MOA (Modifier or additive use); PRP (Properties); USES (Uses)

(alkyl-terminated silicon prepared by Olefin insertion into the H-Si bond of the H-Si(111) surface, and replacement of Cl on the Cl-Si(111) surface by an alkyl group from an alkyllithium reagent)

IT 12385-13-6, Hydrogen atomic, reactions 22537-15-1, Chlorine atomic, reactions

RL: MOA (Modifier or additive use); RCT (Reactant); RACT (Reactant or reagent); USES (Uses)

(alkyl-terminated silicon prepared by Olefin insertion into the H-Si bond of the H-Si(111) surface, and replacement of Cl on the Cl-Si(111) surface by an alkyl group from an alkyllithium reagent)

IT 109-72-8, Butyllithium, reactions 917-54-4, Methyllithium

RL: RCT (Reactant); RACT (Reactant or reagent)

(alkyl-terminated silicon prepared by Olefin insertion into the H-Si bond of the H-Si(111) surface, and replacement of Cl on the Cl-Si(111) surface by an alkyl group from an alkyllithium reagent)

AN 1999:16013 CAPLUS
DN 130:144567
ED Entered STN: 12 Jan 1999
TI Alkyl-terminated Si(111) surfaces: A high-resolution, core level photoelectron spectroscopy study
AU Terry, Jeff; Linford, Matthew R.; Wigren, Christer; Cao, Renyu; Pianetta, Piero; Chidsey, Christopher E. D.
CS Stanford University, Stanford, CA, 94309, USA
SO Journal of Applied Physics (1999), 85(1), 213-221
CODEN: JAPIAU; ISSN: 0021-8979
PB American Institute of Physics
DT Journal
LA English
CC 66-4 (Surface Chemistry and Colloids)
Section cross-reference(s): 22, 73
AB The bonding of alkyl monolayers to Si(111) surfaces has been studied with high-resolution core level photoelectron spectroscopy (PES). Two very different wet-chemical methods have been used to prepare the alkyl monolayers: (i) Olefin insertion into the H-Si bond of the H-Si(111) surface, and (ii) replacement of Cl on the Cl-Si(111) surface by an alkyl group from an alkyllithium reagent. In both cases, PES has revealed a C 1s component shifted to lower binding energy and a Si 2p component shifted to higher binding energy. Both components are attributed to the presence of a C-Si bond at the interface. Along with photoelectron diffraction data [Appl. Phys. Lett. 71, 1056, (1997)], these data are used to show that these two synthetic methods can be used to functionalize the Si(111) surface.
ST alkyl terminated silicon surface photoelectron spectroscopy; passivation chlorine hydrogen terminated silicon
IT Annealing
(annealing alkyl monolayers to Si(111) surfaces studied with high-resolution core level photoelectron spectroscopy)
IT Adsorbed monolayers
Alkyl groups
Chemical chains
(bonding of alkyl monolayers to Si(111) surfaces studied with high-resolution core level photoelectron spectroscopy)
IT Passivation
(novel alkyl **passivation monolayers** on Si(111) surfaces studied with high-resolution core level photoelectron spectroscopy)
IT 2229-07-4D, Methyl, reaction production with Si surface 2492-36-6D, Butyl, reaction production with Si surface 2672-01-7D, Pentyl, reaction production with Si surface 34448-85-6D, Octadecyl, reaction production with Si surface 49765-51-7D, Decyl, reaction production with Si surface
RL: MOA (Modifier or additive use); PRP (Properties); USES (Uses)
(alkyl-terminated silicon prepared by Olefin insertion into the H-Si bond of the H-Si(111) surface, and replacement of Cl on the Cl-Si(111) surface by an alkyl group from an alkyllithium reagent)
IT 12385-13-6, Hydrogen atomic, reactions 22537-15-1, Chlorine atomic, reactions
RL: MOA (Modifier or additive use); RCT (Reactant); RACT (Reactant or reagent); USES (Uses)
(alkyl-terminated silicon prepared by Olefin insertion into the H-Si bond of the H-Si(111) surface, and replacement of Cl on the Cl-Si(111) surface by an alkyl group from an alkyllithium reagent)
IT 109-72-8, Butyllithium, reactions 917-54-4, Methyllithium
RL: RCT (Reactant); RACT (Reactant or reagent)
(alkyl-terminated silicon prepared by Olefin insertion into the H-Si bond of the H-Si(111) surface, and replacement of Cl on the Cl-Si(111) surface by an alkyl group from an alkyllithium reagent)

IT 109-67-1, 1-Pentene 112-88-9, 1-Octadecene 872-05-9, 1-Decene
RL: RCT (Reactant); RACT (Reactant or reagent)
(alkyl-terminated silicon prepared by Olefin insertion of 1-alkenes into
the H-Si bond of the H-Si(111) surface, and replacement of Cl on the
Cl-Si(111) surface by an alkyl group from an alkyllithium reagent)

IT 7440-21-3, Silicon, properties
RL: PEP (Physical, engineering or chemical process); PRP (Properties);
PROC (Process)
(hydrogen-, chlorine-, alkyl-terminated; bonding of alkyl monolayers to
Si(111) surfaces studied with high-resolution core level photoelectron
spectroscopy)

RE.CNT 23 THERE ARE 23 CITED REFERENCES AVAILABLE FOR THIS RECORD

RE

- (1) Chidsey, C; Fourth International Symposium on Cleaning Technology in
Semiconductor Device Manufacturing, (unpublished) 1995
- (2) Coon, P; J Vac Sci Technol B 1992, V10, P221 CAPLUS
- (3) Eastman, D; J Vac Sci Technol 1982, V20, P609 CAPLUS
- (4) Higashi, G; Appl Phys Lett 1990, V56, P656 CAPLUS
- (5) Himpsel, F; Phys Rev B 1988, V38, P6084 CAPLUS
- (6) Hricovini, K; Phys Rev Lett 1993, V70, P1992 CAPLUS
- (7) Hufner, S; Photoelectron Spectroscopy 1995
- (8) Krull, U; Proc SPIE 1988, V906, P49 CAPLUS
- (9) Kusunoki, I; Appl Surf Sci 1992, V59, P95 CAPLUS
- (10) Lapiano-Smith, D; J Appl Phys 1993, V74, P5842 CAPLUS
- (11) Larkins, G; Thin Solid Films 1989, V180, P217 CAPLUS
- (12) Linford, M; J Am Chem Soc 1993, V115, P12631 CAPLUS
- (13) Linford, M; J Am Chem Soc 1995, V117, P3145 CAPLUS
- (14) Linford, M; PhD thesis Stanford University 1996
- (15) Outka, D; J Chem Phys 1988, V88, P4076 CAPLUS
- (16) Outka, D; Phys Rev Lett 1987, V59, P1321 CAPLUS
- (17) Schedel-Niedrig, T; J Phys: Condens Matter 1991, V3A, PS23
- (18) Stinespring, C; J Appl Phys 1989, V65, P1733 CAPLUS
- (19) Taylor, P; J Appl Phys 1989, V65, P1099 CAPLUS
- (20) Terry, J; Appl Phys Lett 1997, V71, P1056 CAPLUS
- (21) Terry, J; J Vac Sci Technol A 1994, V12, P1869 CAPLUS
- (22) Terry, J; Nucl Instrum Methods Phys Res B 1997, V133, P97
- (23) Terry, J; to be published

IT 109-67-1, 1-Pentene 112-88-9, 1-Octadecene 872-05-9, 1-Decene
RL: RCT (Reactant); RACT (Reactant or reagent)
(alkyl-terminated silicon prepared by Olefin insertion of 1-alkenes into
the H-Si bond of the H-Si(111) surface, and replacement of Cl on the
Cl-Si(111) surface by an alkyl group from an alkyllithium reagent)

IT 7440-21-3, Silicon, properties
RL: PEP (Physical, engineering or chemical process); PRP (Properties);
PROC (Process)
(hydrogen-, chlorine-, alkyl-terminated; bonding of alkyl monolayers to
Si(111) surfaces studied with high-resolution core level photoelectron
spectroscopy)

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- (4) Higashi, G; Appl Phys Lett 1990, V56, P656 CAPLUS
- (5) Himpsel, F; Phys Rev B 1988, V38, P6084 CAPLUS
- (6) Hricovini, K; Phys Rev Lett 1993, V70, P1992 CAPLUS
- (7) Hufner, S; Photoelectron Spectroscopy 1995
- (8) Krull, U; Proc SPIE 1988, V906, P49 CAPLUS
- (9) Kusunoki, I; Appl Surf Sci 1992, V59, P95 CAPLUS
- (10) Lapiano-Smith, D; J Appl Phys 1993, V74, P5842 CAPLUS
- (11) Larkins, G; Thin Solid Films 1989, V180, P217 CAPLUS
- (12) Linford, M; J Am Chem Soc 1993, V115, P12631 CAPLUS
- (13) Linford, M; J Am Chem Soc 1995, V117, P3145 CAPLUS
- (14) Linford, M; PhD thesis Stanford University 1996
- (15) Outka, D; J Chem Phys 1988, V88, P4076 CAPLUS
- (16) Outka, D; Phys Rev Lett 1987, V59, P1321 CAPLUS
- (17) Schedel-Niedrig, T; J Phys: Condens Matter 1991, V3A, PS23
- (18) Stinespring, C; J Appl Phys 1989, V65, P1733 CAPLUS
- (19) Taylor, P; J Appl Phys 1989, V65, P1099 CAPLUS
- (20) Terry, J; Appl Phys Lett 1997, V71, P1056 CAPLUS
- (21) Terry, J; J Vac Sci Technol A 1994, V12, P1869 CAPLUS
- (22) Terry, J; Nucl Instrum Methods Phys Res B 1997, V133, P97
- (23) Terry, J; to be published

AN 2002:142026 CAPLUS
DN 136:287463
ED Entered STN: 22 Feb 2002
TI Nanoscale phosphorous atom arrays created using STM for the fabrication of a silicon-based quantum computer
AU O'Brien, J. L.; Schofield, S. R.; Simmons, M. Y.; Clark, Robert G.; Dzurak, Andrew S.; Curson, N. J.; Kane, Bruce E.; McAlpine, N. S.; Hawley, Marilyn E.; Brown, G. W.
CS Centre for Quantum Computer Technology, University of New South Wales, Sydney, 2052, Australia
SO Proceedings of SPIE-The International Society for Optical Engineering (2001), 4590(BioMEMS and Smart Nanostructures), 299-309
CODEN: PSISDG; ISSN: 0277-786X
PB SPIE-The International Society for Optical Engineering
DT Journal
LA English
CC 76-14 (Electric Phenomena)
AB Quantum computers offer the promise of formidable computational power for certain tasks. Of the various possible phys. implementations of such a device, silicon based architectures are attractive for their scalability and ease of integration with existing silicon technol. These designs use either the electron or nuclear spin state of single donor atoms to store quantum information. Here we describe a strategy to fabricate an array of single phosphorus atoms in silicon for the construction of such a silicon based quantum computer. We demonstrate the controlled placement of single phosphorus bearing mols. on a silicon surface. This has been achieved by patterning a hydrogen monolayer resist with a scanning tunneling microscope (STM) tip and exposing the patterned surface to phosphine (PH₃) mols. We also describe preliminary studies into a process to incorporate these surface phosphorus atoms into the silicon crystal at the array sites.
ST STM lithog hydrogen desorption phosphine adsorption silicon quantum computer
IT Adsorbed monolayers
Chemisorption
Passivation
Scanning tunneling microscopy
Thermal decomposition
(nanoscale phosphorous atom arrays created using STM for the fabrication of a silicon-based quantum computer)
IT Desorption
(selective; nanoscale phosphorous atom arrays created using STM for the fabrication of a silicon-based quantum computer)
IT Lithography
(submicron, STM; nanoscale phosphorous atom arrays created using STM for the fabrication of a silicon-based quantum computer)
IT 7723-14-0, Phosphorus-31, processes
RL: CPS (Chemical process); DEV (Device component use); MOA (Modifier or additive use); PEP (Physical, engineering or chemical process); PROC (Process); USES (Uses)
(nanoscale phosphorous atom arrays created using STM for the fabrication of a silicon-based quantum computer)
IT 7440-21-3, Silicon, processes
RL: CPS (Chemical process); DEV (Device component use); PEP (Physical, engineering or chemical process); PROC (Process); USES (Uses)
(nanoscale phosphorous atom arrays created using STM for the fabrication of a silicon-based quantum computer)
IT 7803-51-2, Phosphine
RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); RCT (Reactant); PROC (Process); RACT (Reactant or reagent)
(nanoscale phosphorous atom arrays created using STM for the

AN 2002:142026 CAPLUS
DN 136:287463
ED Entered STN: 22 Feb 2002
TI Nanoscale phosphorous atom arrays created using STM for the fabrication of a silicon-based quantum computer
AU O'Brien, J. L.; Schofield, S. R.; Simmons, M. Y.; Clark, Robert G.; Dzurak, Andrew S.; Curson, N. J.; Kane, Bruce E.; McAlpine, N. S.; Hawley, Marilyn E.; Brown, G. W.
CS Centre for Quantum Computer Technology, University of New South Wales, Sydney, 2052, Australia
SO Proceedings of SPIE-The International Society for Optical Engineering (2001), 4590(BioMEMS and Smart Nanostructures), 299-309
CODEN: PSISDG; ISSN: 0277-786X
PB SPIE-The International Society for Optical Engineering
DT Journal
LA English
CC 76-14 (Electric Phenomena)
AB Quantum computers offer the promise of formidable computational power for certain tasks. Of the various possible phys. implementations of such a device, silicon based architectures are attractive for their scalability and ease of integration with existing silicon technol. These designs use either the electron or nuclear spin state of single donor atoms to store quantum information. Here we describe a strategy to fabricate an array of single phosphorus atoms in silicon for the construction of such a silicon based quantum computer. We demonstrate the controlled placement of single phosphorus bearing mols. on a silicon surface. This has been achieved by patterning a hydrogen monolayer resist with a scanning tunneling microscope (STM) tip and exposing the patterned surface to phosphine (PH₃) mols. We also describe preliminary studies into a process to incorporate these surface phosphorus atoms into the silicon crystal at the array sites.
ST STM lithog hydrogen desorption phosphine adsorption silicon quantum computer
IT Adsorbed monolayers
Chemisorption
Passivation
Scanning tunneling microscopy
Thermal decomposition
(nanoscale phosphorous atom arrays created using STM for the fabrication of a silicon-based quantum computer)
IT Desorption
(selective; nanoscale phosphorous atom arrays created using STM for the fabrication of a silicon-based quantum computer)
IT Lithography
(submicron, STM; nanoscale phosphorous atom arrays created using STM for the fabrication of a silicon-based quantum computer)
IT 7723-14-0, Phosphorus-31, processes
RL: CPS (Chemical process); DEV (Device component use); MOA (Modifier or additive use); PEP (Physical, engineering or chemical process); PROC (Process); USES (Uses)
(nanoscale phosphorous atom arrays created using STM for the fabrication of a silicon-based quantum computer)
IT 7440-21-3, Silicon, processes
RL: CPS (Chemical process); DEV (Device component use); PEP (Physical, engineering or chemical process); PROC (Process); USES (Uses)
(nanoscale phosphorous atom arrays created using STM for the fabrication of a silicon-based quantum computer)
IT 7803-51-2, Phosphine
RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); RCT (Reactant); PROC (Process); RACT (Reactant or reagent)
(nanoscale phosphorous atom arrays created using STM for the

fabrication of a silicon-based quantum computer)

IT 12385-13-6, Hydrogen atom, processes

RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); PROC (Process)

(**passivation monolayer**; nanoscale phosphorous atom arrays created using STM for the fabrication of a silicon-based quantum computer)

RE.CNT 45 THERE ARE 45 CITED REFERENCES AVAILABLE FOR THIS RECORD

RE

fabrication of a silicon-based quantum computer)

IT 12385-13-6, Hydrogen atom, processes

RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); PROC (Process)

(**passivation monolayer**; nanoscale phosphorous atom arrays created using STM for the fabrication of a silicon-based quantum computer)

RE.CNT 45 THERE ARE 45 CITED REFERENCES AVAILABLE FOR THIS RECORD

RE

AN 1982:446413 CAPLUS
 DN 97:46413
 ED Entered STN: 12 May 1984
 TI Nature of current maximums on unsteady-state polarization curves of indium
 in weakly alkaline solutions
 AU Sebek, B.; Juodiene, T.; Juodkazis, K.
 CS USSR
 SO Issled. Obl. Osazhdeniya Met., Mater. Resp. Konf. Elektrokhim. Lit. SSR,
 18th (1981), 201-6 Publisher: Akad. Nauk Lit. SSR, Inst. Khim. Khim.
 Tekhnol., Vilnius, USSR.
 CODEN: 47URAG
 DT Conference
 LA Russian
 CC 72-2 (Electrochemistry)
 AB A comparison of exptl. and calculated polarization curves for the discharge of
 an In hydroxide monolayer from an In electrode in NaClO4 solns. (ionic
 strength 3M, pH 12, temperature 20°) shows the electrode to be a
 2nd-order metal-oxide electrode. During the cathodic process, the surface
 concentration of (OH)- is determined by the rate of hydroxide reduction ($M +$
 $n(OH)^- \rightarrow M(OH)_n + ne$) and the rate of removal into the bulk of the
 electrolyte of the (OH)- formed. In the anodic process, the (OH)- surface
 concentration is determined by the electrolyte pH and the ion supply from the
 bulk of the electrolyte. At $n = 1$, the coincidence of the curves indicates the
 cathodic current maximum to be due to the discharge of InOH, not In(OH)3.
 The InOH monolayer is the main course of passivation of the In electrode.
 ST current max unsteady polarization indium; hydroxide indium
passivation monolayer electrode
 IT Electric current
 (maximum, in unsteady-state polarization of indium)
 IT Passivation
 (of indium, in unsteady-state polarization)
 IT Electrolytic polarization
 (unsteady-state, current maximum in, of indium)
 IT 7440-74-6, properties
 RL: PRP (Properties)
 (electrolytic polarization of, unsteady-state, current maximum in)
 IT 32365-64-3P
 RL: FORM (Formation, nonpreparative); PREP (Preparation)
 (formation of, in unsteady-state polarization of indium, with current
 maximum)

AN 1982:446413 CAPLUS
 DN 97:46413
 ED Entered STN: 12 May 1984
 TI Nature of current maximums on unsteady-state polarization curves of indium
 in weakly alkaline solutions
 AU Sebek, B.; Juodiene, T.; Juodkazis, K.
 CS USSR
 SO Issled. Obl. Osazhdeniya Met., Mater. Resp. Konf. Elektrokhim. Lit. SSR,
 18th (1981), 201-6 Publisher: Akad. Nauk Lit. SSR, Inst. Khim. Khim.
 Tekhnol., Vilnius, USSR.
 CODEN: 47URAG
 DT Conference
 LA Russian
 CC 72-2 (Electrochemistry)
 AB A comparison of exptl. and calculated polarization curves for the discharge of
 an In hydroxide monolayer from an In electrode in NaClO4 solns. (ionic
 strength 3M, pH 12, temperature 20°) shows the electrode to be a
 2nd-order metal-oxide electrode. During the cathodic process, the surface
 concentration of (OH)- is determined by the rate of hydroxide reduction ($M +$
 $n(OH)^- \rightarrow M(OH)_n + ne$) and the rate of removal into the bulk of the
 electrolyte of the (OH)- formed. In the anodic process, the (OH)- surface
 concentration is determined by the electrolyte pH and the ion supply from the
 bulk of the electrolyte. At $n = 1$, the coincidence of the curves indicates the
 cathodic current maximum to be due to the discharge of InOH, not In(OH)3.
 The InOH monolayer is the main course of passivation of the In electrode.
 ST current max unsteady polarization indium; hydroxide indium
passivation monolayer electrode
 IT Electric current
 (maximum, in unsteady-state polarization of indium)
 IT Passivation
 (of indium, in unsteady-state polarization)
 IT Electrolytic polarization
 (unsteady-state, current maximum in, of indium)
 IT 7440-74-6, properties
 RL: PRP (Properties)
 (electrolytic polarization of, unsteady-state, current maximum in)
 IT 32365-64-3P
 RL: FORM (Formation, nonpreparative); PREP (Preparation)
 (formation of, in unsteady-state polarization of indium, with current
 maximum)

AN 1986:468983 CAPLUS
 DN 105:68983
 ED Entered STN: 23 Aug 1986
 TI The cation **monolayer** model for metal **passivation**. II.
 Kinetics of the active-passive transition
 AU Griffin, G. L.
 CS Dep. Chem. Eng. Mater. Sci., Univ. Minnesota, Minneapolis, MN, 55455, USA
 SO Journal of the Electrochemical Society (1986), 133(7), 1315-20
 CODEN: JESOAN; ISSN: 0013-4651
 DT Journal
 LA English
 CC 72-6 (Electrochemistry)
 Section cross-reference(s): 67
 AB An anal. was made of the transient **passivation** kinetics expected
 for the recently proposed cation **monolayer** model for passive
 film formation. The theor. framework is developed using classical
 nucleation theory, as applied to the phase transition for the formation of
 a cation **monolayer** stabilized by attractive interactions between
 neighboring cations. Transient **passivation** curves are calculated
 for current vs. time following a step change of the **electrode**
 potential between active and passive potential regions, and for current
 vs. **voltage** during linear potentiodynamic sweeps in both
 directions across the transition potential. For the transient cases, the
 potential and amplitude of the maximum current during the active-passive
 transition are functions of the potentiodynamic sweep rate, and a
 pronounced hysteresis loop is predicted during potential cycles around the
 active-passive transition.
 ST kinetics active passive transition model; **passivation**
 electrochem adsorbed cation model
 IT Cations
 (adsorbed, kinetics of active-passive transition in relation to)
 IT Adsorbed substances
 (cations, kinetics of active-passive transition in relation to)
 IT Kinetics of **passivation**
Passivation
 (electrochem., cation **monolayer** model for, active-passive
 transition in relation to)
 IT Kinetics of oxidation
 (electrochem., of metals, adsorbed cation model in relation to)

ANSWER 6 OF 9 CAPLUS COPYRIGHT 2004 ACS on STN

AN 1986:468983 CAPLUS
DN 105:68983
ED Entered STN: 23 Aug 1986
TI The cation **monolayer** model for metal **passivation**. II.
Kinetics of the active-passive transition
AU Griffin, G. L.
CS Dep. Chem. Eng. Mater. Sci., Univ. Minnesota, Minneapolis, MN, 55455, USA
SO Journal of the Electrochemical Society (1986), 133(7), 1315-20
CODEN: JESQAN; ISSN: 0013-4651
DT Journal
LA English
CC 72-6 (Electrochemistry)
Section cross-reference(s): 67
AB An anal. was made of the transient **passivation** kinetics expected
for the recently proposed cation **monolayer** model for passive
film formation. The theor. framework is developed using classical
nucleation theory, as applied to the phase transition for the formation of
a cation **monolayer** stabilized by attractive interactions between
neighboring cations. Transient **passivation** curves are calculated
for current vs. time following a step change of the **electrode**
potential between active and passive potential regions, and for current
vs. **voltage** during linear potentiodynamic sweeps in both
directions across the transition potential. For the transient cases, the
potential and amplitude of the maximum current during the active-passive
transition are functions of the potentiodynamic sweep rate, and a
pronounced hysteresis loop is predicted during potential cycles around the
active-passive transition.
ST kinetics active passive transition model; **passivation**
electrochem adsorbed cation model
IT Cations
(adsorbed, kinetics of active-passive transition in relation to)
IT Adsorbed substances
(cations, kinetics of active-passive transition in relation to)
IT Kinetics of **passivation**
Passivation
(electrochem., cation **monolayer** model for, active-passive
transition in relation to)
IT Kinetics of oxidation
(electrochem., of metals, adsorbed cation model in relation to)

ANSWER 10 OF 10 CAPLUS COPYRIGHT 2004 ACS on STN

AN 1969:466634 CAPLUS

DN 71:66634

ED Entered STN: 12 May 1984

TI **Passivation** of zinc amalgam in alkaline solutions

AU Armstrong, Ronald Dixon; Bulman, G. M.; Thirsk, Harold R.

CS Univ. Newcastle upon Tyne, Newcastle upon Tyne, UK

SO Journal of Electroanalytical Chemistry and Interfacial Electrochemistry
(1969), 22(1), 55-62

CODEN: JEIEBC; ISSN: 0022-0728

DT Journal

LA English

CC 77 (Electrochemistry)

AB The **passivation** of 1 atomic % Zn amalgam in 0.01-0.1M NaOH containing NaCl, NaNO₃, and Na₂SO₄ supporting electrolyte is studied by sq. pulse potentiostatic measurements, impedance measurements, and electron diffraction of the surface film. The **passivation** is due to the formation of a phase **monolayer** on the **electrode** surface. The layer could not pos. be identified as ZnO because the techniques used were not in situ and there was some evidence for Zn hydroxides at -0.7 v. The layer is formed by a mechanism involving 2 dimensional nucleation. No specific OH⁻ adsorption can be **detected** at potentials prior to the active-passive transition.

ST **passivation** Zn amalgams; amalgams Zn **passivation**; zinc amalgams **passivation**; alk solns Zn amalgams **passivation**; surface layers Zn amalgams **passivation**

IT Zinc alloys, containing
(amalgams, **passivation** of, in alkaline solns.)

IT **Passivation**
(of zinc amalgams, in alkaline solns.)

IT Amalgams
(zinc, **passivation** of, in alkaline solns.)

ANSWER 10 OF 10 CAPLUS COPYRIGHT 2004 ACS on STN

AN 1969:466634 CAPLUS

DN 71:66634

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TI **Passivation** of zinc amalgam in alkaline solutions

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DT Journal

LA English

CC 77 (Electrochemistry)

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ST **passivation** Zn amalgams; amalgams Zn **passivation**; zinc amalgams **passivation**; alk solns Zn amalgams **passivation**; surface layers Zn amalgams **passivation**

IT Zinc alloys, containing
(amalgams, **passivation** of, in alkaline solns.)

IT **Passivation**
(of zinc amalgams, in alkaline solns.)

IT Amalgams
(zinc, **passivation** of, in alkaline solns.)

AN 1992:243703 CAPLUS
DN 116:243703
ED Entered STN: 13 Jun 1992
TI X-ray photoelectron spectroscopic studies of interfacial chemistry at
n-type silicon/liquid junctions
AU Tufts, Bruce J.; Kumar, Amit; Bansal, Ashish; Lewis, Nathan S.
CS Div. Chem. Chem. Eng., California Inst. Technol., Pasadena, CA, 91125, USA
SO Journal of Physical Chemistry (1992), 96(11), 4581-92
CODEN: JPCHAX; ISSN: 0022-3654
DT Journal
LA English
CC 72-2 (Electrochemistry)
Section cross-reference(s): 66, 74, 76
AB The surface chemical of n-type Si **electrodes** that had been etched,
exposed to electrolyte, and electrochem. cycled has been probed using
high-resolution XPS. The n-Si surfaces etched in hydrofluoric acid-ethanol
solns. (in air or N₂ ambients) displayed spectra in the Si 2p region that
were free of **detectable** substrate oxide signals (≤ 5
+ 10⁻¹¹ mol cm⁻² SiO₂; equivalent to $\leq 4\%$ of a **monolayer**
). Exposure of HF-C₂H₅OH etched or 49% HF(aqueous) etched n-Si surfaces to an
electrolyte solution containing CH₃OH, dimethylferrocene (Me₂Fc), and
dimethylferricenium (Me₂Fc⁺) generated very low levels, $\leq (2 \pm$
1) + 10⁻¹⁰ mol cm⁻², of silicon suboxides. Only sub-
monolayer levels of SiO_x, (4 \pm 2) + 10⁻¹⁰ mol cm⁻², were
detected after electrochem. cycling of illuminated n-Si anodes in
contact with CH₃OH-Me₂Fc⁺/0 electrolytes. Even n-Si photoanodes
maintained at short circuit with the CH₃OH-Me₂Fc⁺/0 electrolyte for
substantial periods (>1000 C cm⁻² anodic charge passed) formed less than a
single **monolayer** of strained SiO₂ at the silicon surface.
Deliberate anodization of the Si surface in these electrolyte solns.
yielded controlled amts. of thicker (8-10 Å) SiO₂ overlayers; these
overlayers provided a useful oxide for the formation of high-performance
metal-insulator-semiconductor device structures. These studies
demonstrate that HF-C₂H₅OH- or HF(aqueous)-etched n-Si surfaces are remarkably
resistant to oxide formation during photoelectrochem. cycling in
CH₃OH-based electrolytes, and that the outstanding photoelectrochem. I-V
properties of the n-Si/CH₃OH-Me₂Fc⁺/0 junction are not a result of
formation of a passivating oxide overlayers on the Si surface.
ST silicon electrolyte interface XPS; surface analysis silicon oxide; etching
passivation silicon surface; photoanode silicon semiconductor
junction
IT Anodization
Etching
 Passivation
 (of silicon, in alc.-electrolyte solution)
IT Surface analysis
 (of silicon, in electrolyte solution, etching effect on)
IT Semiconductor junctions
 (silicon-electrolyte, **passivation** in)
IT Interface
 (silicon-electrolyte, silica formation at)
IT Redox reaction
 (photoelectrochem., of dimethylferrocene, on silicon)
IT Anodes
 (photoelectrochem., silicon)
IT 7791-03-9, Lithium perchlorate
RL: PRP (Properties)
 (electrochem. anodization and electrochem. redox reaction of
 dimethylferrocene in solution containing)
IT 7664-39-3, Hydrofluoric acid, reactions
RL: RCT (Reactant); RACT (Reactant or reagent)

AN 1992:243703 CAPLUS
DN 116:243703
ED Entered STN: 13 Jun 1992
TI X-ray photoelectron spectroscopic studies of interfacial chemistry at
n-type silicon/liquid junctions
AU Tufts, Bruce J.; Kumar, Amit; Bansal, Ashish; Lewis, Nathan S.
CS Div. Chem. Chem. Eng., California Inst. Technol., Pasadena, CA, 91125, USA
SO Journal of Physical Chemistry (1992), 96(11), 4581-92
CODEN: JPCHAX; ISSN: 0022-3654
DT Journal
LA English
CC 72-2 (Electrochemistry)
Section cross-reference(s): 66, 74, 76
AB The surface chemical of n-type Si **electrodes** that had been etched,
exposed to electrolyte, and electrochem. cycled has been probed using
high-resolution XPS. The n-Si surfaces etched in hydrofluoric acid-ethanol
solns. (in air or N₂ ambients) displayed spectra in the Si 2p region that
were free of **detectable** substrate oxide signals (≤ 5
+ 10⁻¹¹ mol cm⁻² SiO₂; equivalent to $\leq 4\%$ of a **monolayer**
). Exposure of HF-C₂H₅OH etched or 49% HF(aqueous) etched n-Si surfaces to an
electrolyte solution containing CH₃OH, dimethylferrocene (Me₂Fc), and
dimethylferricenium (Me₂Fc⁺) generated very low levels, $\leq (2 \pm$
1) + 10⁻¹⁰ mol cm⁻², of silicon suboxides. Only sub-
monolayer levels of SiO_x, $(4 \pm 2) + 10^{-10}$ mol cm⁻², were
detected after electrochem. cycling of illuminated n-Si anodes in
contact with CH₃OH-Me₂Fc⁺/0 electrolytes. Even n-Si photoanodes
maintained at short circuit with the CH₃OH-Me₂Fc⁺/0 electrolyte for
substantial periods (>1000 C cm⁻² anodic charge passed) formed less than a
single **monolayer** of strained SiO₂ at the silicon surface.
Deliberate anodization of the Si surface in these electrolyte solns.
yielded controlled amts. of thicker (8-10 Å) SiO₂ overlayers; these
overlayers provided a useful oxide for the formation of high-performance
metal-insulator-semiconductor device structures. These studies
demonstrate that HF-C₂H₅OH- or HF(aqueous)-etched n-Si surfaces are remarkably
resistant to oxide formation during photoelectrochem. cycling in
CH₃OH-based electrolytes, and that the outstanding photoelectrochem. I-V
properties of the n-Si/CH₃OH-Me₂Fc⁺/0 junction are not a result of
formation of a passivating oxide overlayers on the Si surface.
ST silicon electrolyte interface XPS; surface analysis silicon oxide; etching
passivation silicon surface; photoanode silicon semiconductor
junction
IT Anodization
Etching
Passivation
(of silicon, in alc.-electrolyte solution)
IT Surface analysis
(of silicon, in electrolyte solution, etching effect on)
IT Semiconductor junctions
(silicon-electrolyte, **passivation** in)
IT Interface
(silicon-electrolyte, silica formation at)
IT Redox reaction
(photoelectrochem., of dimethylferrocene, on silicon)
IT Anodes
(photoelectrochem., silicon)
IT 7791-03-9, Lithium perchlorate
RL: PRP (Properties)
(electrochem. anodization and electrochem. redox reaction of
dimethylferrocene in solution containing)
IT 7664-39-3, Hydrofluoric acid, reactions
RL: RCT (Reactant); RACT (Reactant or reagent)

(etching with, of silicon, silicon oxide formation in relation to)

IT 11126-22-0P, Silicon oxide
RL: FORM (Formation, nonpreparative); PREP (Preparation)
(formation of, at silicon interface, during etching)

IT 7631-86-9P, Silicon dioxide, preparation
RL: FORM (Formation, nonpreparative); PREP (Preparation)
(formation of, during anodization of silicon, in alc. solution)

IT 7440-21-3, Silicon, properties
RL: PRP (Properties)
(interface anal. of, in alc. solution, with dimethylferrocene)

IT 64-17-5, Ethanol, uses
RL: USES (Uses)
(photoelectrochem. cycling of silicon in solution of, oxide formation in relation to)

IT 67-56-1, Methanol, uses
RL: USES (Uses)
(photoelectrochem. etching of silicon in solution containing, oxide formation in relation to)

IT 1291-47-0, Dimethylferrocene 12276-63-0
RL: RCT (Reactant); RACT (Reactant or reagent)
(redox reaction of, photoelectrochem., on silicon)

(etching with, of silicon, silicon oxide formation in relation to)

IT 11126-22-0P, Silicon oxide
 RL: FORM (Formation, nonpreparative); PREP (Preparation)
 (formation of, at silicon interface, during etching)

IT 7631-86-9P, Silicon dioxide, preparation
 RL: FORM (Formation, nonpreparative); PREP (Preparation)
 (formation of, during anodization of silicon, in alc. solution)

IT 7440-21-3, Silicon, properties
 RL: PRP (Properties)
 (interface anal. of, in alc. solution, with dimethylferrocene)

IT 64-17-5, Ethanol, uses
 RL: USES (Uses)
 (photoelectrochem. cycling of silicon in solution of, oxide formation in relation to)

IT 67-56-1, Methanol, uses
 RL: USES (Uses)
 (photoelectrochem. etching of silicon in solution containing, oxide formation in relation to)

IT 1291-47-0, Dimethylferrocene 12276-63-0
 RL: RCT (Reactant); RACT (Reactant or reagent)
 (redox reaction of, photoelectrochem., on silicon)

AN 1968:464095 CAPLUS

DN 69:64095

ED Entered STN: 12 May 1984

TI **Passivation** of anodic reactions

AU Schuldiner, Sigmund

CS Nav. Res. Lab., Washington, DC, USA

SO Journal of the Electrochemical Society (1968), 115(9), 897-9

CODEN: JESOAN; ISSN: 0013-4651

DT Journal

LA English

CC 77 (Electrochemistry)

AB Extending the Wagner definition of passivity to anodic reactions of chemical species on inert **electrodes**, it is shown that initiation of **passivation** of a Pt **electrode** for the H oxidation reaction can be explained by small amts. (fraction of a **monolayer**) of adsorbed anions. Anion adsorption can effectively reduce the active **electrode** area, but the major **passivation** effect is the poisoning of catalytic sites which retard the catalytic reaction so that in most of the region where **passivation** occurs the reaction rate is controlled by the increased free energy of activation with increased potential. The change in sign from pos. to neg. of the $dE/d(\log i)$ kinetic relation can be explained by adsorption of a small number of anions and is limited when the active sites are essentially saturated. Adsorbed O atoms in addition to sulfate ions can have a strong effect on the catalytic activity of Pt for the H oxidation reaction. This concept may be extended to other retarded anodic reactions and to the **passivation** of Fe in particular.

ST **passivation** anodic reactions; anodic reactions**passivation**; adsorption **passivation** anodic reactionsIT **Passivation**

(of platinum oxidation catalysts, adsorbed oxygen atoms and sulfate ions in relation to)

IT 7782-44-7, uses and miscellaneous

RL: USES (Uses)

(absorbed by platinum, catalytic oxidation of hydrogen in relation to)

IT 14808-79-8, Sulfate, properties

RL: PRP (Properties)

(absorbed by platinum, catalytic oxidation of hydrogen in relation to)

IT 7440-06-4, uses and miscellaneous

RL: CAT (Catalyst use); USES (Uses)

(oxidation catalysts, adsorbed oxygen and sulfate in relation to)

IT 7439-89-6, reactions

RL: RCT (Reactant); RACT (Reactant or reagent)

(passivation of)

AN 1968:464095 CAPLUS

DN 69:64095

ED Entered STN: 12 May 1984

TI **Passivation** of anodic reactions

AU Schuldiner, Sigmund

CS Nav. Res. Lab., Washington, DC, USA

SO Journal of the Electrochemical Society (1968), 115(9), 897-9

CODEN: JESOAN; ISSN: 0013-4651

DT Journal

LA English

CC 77 (Electrochemistry)

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ST **passivation** anodic reactions; anodic reactionsIT **passivation**; adsorption **passivation** anodic reactionsIT **Passivation**

(of platinum oxidation catalysts, adsorbed oxygen atoms and sulfate ions in relation to)

IT 7782-44-7, uses and miscellaneous

RL: USES (Uses)

(adsorbed by platinum, catalytic oxidation of hydrogen in relation to)

IT 14808-79-8, Sulfate, properties

RL: PRP (Properties)

(adsorbed by platinum, catalytic oxidation of hydrogen in relation to)

IT 7440-06-4, uses and miscellaneous

RL: CAT (Catalyst use); USES (Uses)

(oxidation catalysts, adsorbed oxygen and sulfate in relation to)

IT 7439-89-6, reactions

RL: RCT (Reactant); RACT (Reactant or reagent)

(**passivation** of)

AN 1995:134431 CAPLUS
 DN 122:40801
 ED Entered STN: 08 Nov 1994
 TI **Passivation** and gating at the **electrode**-solution interface via monomolecular Langmuir-Blodgett films. Mechanism of alkanethiol **binding** to gold
 AU Majda, Marcin
 CS Department Chemistry, University California, Berkeley, CA, 94720, USA
 SO ACS Symposium Series (1994), 561(INTERFACIAL DESIGN AND CHEMICAL SENSING), 135-44
 CODEN: ACSMC8; ISSN: 0097-6156
 DT Journal
 LA English
 CC 72-2 (Electrochemistry)
 Section cross-reference(s): 56, 66
 AB To define molecularly active sites at the **electrode** surface, monomol. Langmuir-Blodgett films are being designed to carry out two functions: **passivation** and gating. This new strategy requires one to produce monomol. LB films of exquisitely low defect level. To accomplish this, the authors have studied the mechanism of octadecanethiol (C18SH) **binding** to gold under potentiostatic conditions, to better understand C18SH passivating properties. The approach involves constant potential current measurements taken during the LB transfer of **monolayers** that contain C18SH from the air/water interface onto gold substrates. Thiol-gold coupling involves a potential-dependent partial electron transfer from sulfur to gold of 0.26 electron per thiol at -0.3 V, and 0.4 electron at 0.7 V vs. SCE. The requirements of electro-neutrality and zero capacitance of the emersed alkanethiol-coated gold surface lead to a postulate that an equivalent number of protons are released during the C18SH LB transfer.
 ST octadecanethiol **binding** gold potentiostatic condition; **passivation** gating **electrode** soln interface; alkanethiol **binding** gold **electrode**
 IT Electron exchange and Charge transfer
 (in **binding** of octadecanethiol on gold)
 IT **Passivation**
 (passivation and gating at **electrode**-solution interface via monomol. Langmuir-Blodgett films)
 IT Electric current
 (transients; in Langmuir-Blodgett transfer of octadecanethiol and octadecanethiol/octadecyl alc. **monolayers** from HClO4 to gold)
 IT Chemisorption
 (electrochem., of octadecanethiol on gold)
 IT 7601-90-3, Perchloric acid, uses
 RL: NUU (Other use, unclassified); PRP (Properties); USES (Uses)
 (current-time transients for Langmuir-Blodgett transfer of octadecanethiol and octadecanethiol/octadecyl alc. **monolayers** from HClO4 to gold from)
 IT 2885-00-9, Octadecanethiol
 RL: PEP (Physical, engineering or chemical process); PRP (Properties); PROC (Process)
 (mechanism of octadecanethiol **binding** to gold under potentiostatic conditions)
 IT 7440-57-5, Gold, uses
 RL: DEV (Device component use); PEP (Physical, engineering or chemical process); PRP (Properties); PROC (Process); USES (Uses)
 (passivation and gating at **electrode**-solution interface via monomol. Langmuir-Blodgett films and mechanism of alkanethiol **binding** to gold)
 IT 112-92-5, Octadecyl alcohol
 RL: PEP (Physical, engineering or chemical process); PRP (Properties);

AN 1995:134431 CAPLUS
DN 122:40801
ED Entered STN: 08 Nov 1994
TI **Passivation** and gating at the **electrode-solution**
interface via monomolecular Langmuir-Blodgett films. Mechanism of
alkanethiol **binding** to gold
AU Majda, Marcin
CS Department Chemistry, University California, Berkeley, CA, 94720, USA
SO ACS Symposium Series (1994), 561(INTERFACIAL DESIGN AND CHEMICAL
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CODEN: ACSMC8; ISSN: 0097-6156
DT Journal
LA English
CC 72-2 (Electrochemistry)
Section cross-reference(s): 56, 66
AB To define molecularly active sites at the **electrode** surface,
monomol. Langmuir-Blodgett films are being designed to carry out two
functions: **passivation** and gating. This new strategy requires
one to produce monomol. LB films of exquisitely low defect level. To
accomplish this, the authors have studied the mechanism of octadecanethiol
(C18SH) **binding** to gold under potentiostatic conditions, to
better understand C18SH passivating properties. The approach involves
constant potential current measurements taken during the LB transfer of
monolayers that contain C18SH from the air/water interface onto
gold substrates. Thiol-gold coupling involves a potential-dependent
partial electron transfer from sulfur to gold of 0.26 electron per thiol
at -0.3 V, and 0.4 electron at 0.7 V vs. SCE. The requirements of
electro-neutrality and zero capacitance of the emersed alkanethiol-coated
gold surface lead to a postulate that an equivalent number of protons are
released during the C18SH LB transfer.
ST octadecanethiol **binding** gold potentiostatic condition;
passivation gating **electrode** soln interface; alkanethiol
binding gold **electrode**
IT Electron exchange and Charge transfer
(in **binding** of octadecanethiol on gold)
IT **Passivation**
(**passivation** and gating at **electrode-solution**
interface via monomol. Langmuir-Blodgett films)
IT Electric current
(transients; in Langmuir-Blodgett transfer of octadecanethiol and
octadecanethiol/octadecyl alc. **monolayers** from HClO4 to gold)
IT Chemisorption
(electrochem., of octadecanethiol on gold)
IT 7601-90-3, Perchloric acid, uses
RL: NUU (Other use, unclassified); PRP (Properties); USES (Uses)
(current-time transients for Langmuir-Blodgett transfer of
octadecanethiol and octadecanethiol/octadecyl alc. **monolayers**
from HClO4 to gold from)
IT 2885-00-9, Octadecanethiol
RL: PEP (Physical, engineering or chemical process); PRP (Properties);
PROC (Process)
(mechanism of octadecanethiol **binding** to gold under
potentiostatic conditions)
IT 7440-57-5, Gold, uses
RL: DEV (Device component use); PEP (Physical, engineering or chemical
process); PRP (Properties); PROC (Process); USES (Uses)
(**passivation** and gating at **electrode-solution**
interface via monomol. Langmuir-Blodgett films and mechanism of
alkanethiol **binding** to gold)
IT 112-92-5, Octadecyl alcohol
RL: PEP (Physical, engineering or chemical process); PRP (Properties);

PROC (Process)

(**passivation** and gating of gold **electrode** with
Langmuir-Blodgett film of octadecanethiol and)

=>

PROC (Process)

(**passivation** and gating of gold **electrode** with
Langmuir-Blodgett film of octadecanethiol and)

=>

AN 1994:446193 CAPLUS
 DN 121:46193
 ED Entered STN: 23 Jul 1994
 TI Electro-optic waveguide deflector using a nonlinear optic film or liquid-crystal overlay cell for use in an optical pickup head
 IN Revelli, Joseph F., Jr.; Penner, Thomas L.; Armstrong, Nancy J.; Robello, Douglas R.; Schildkraut, Jay S.
 PA Eastman Kodak Co., USA
 SO U.S., 23 pp.
 CODEN: USXXAM
 DT Patent
 LA English
 IC ICM G02B006-10
 NCL 385008000
 CC 73-11 (Optical, Electron, and Mass Spectroscopy and Other Related Properties)
 Section cross-reference(s): 74, 75

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	US 5291567	A	19940301	US 1992-916422	19920721
	JP 06222400	A2	19940812	JP 1993-179070	19930720
PRAI	US 1992-916422		19920721		

CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
US 5291567	ICM	G02B006-10
	NCL	385008000

AB Electrooptical waveguide deflectors, appropriate for use in optical pickup heads, use any film exhibiting high second order susceptibility such as nonlinear optic organic Langmuir-Blodgett films or nonlinear optic organic poled

polymer films, or a liquid-crystal overlay cell. The deflector comprises a base support, a planar **electrode** layer disposed on the base support, a first buffer layer atop the first **electrode** layer, and an optical waveguide layer overlying the first buffer layer and planar **electrode**. When nonlinear optic films are used to form the waveguide layer, a second buffer layer is disposed atop the waveguide layer, and a pair of spaced **electrodes** is disposed atop the second buffer layer. When a nematic-type liquid-crystal overlay cell is used, it is disposed atop a **passive** dielec. waveguide, and a pair of spaced **electrodes** is disposed on the under surface of the liquid-crystal cell cover plate. The spaced **electrodes** are shaped so that selectively applying an elec. field causes deflection to vary with the applied **voltage** according to the geometrical configuration of the spaced **electrodes**. Methods for fabricating the deflectors are also described.

ST nonlinear optical film electrooptical waveguide deflector; liq crystal overlay cell waveguide deflector; Langmuir Blodgett film electrooptical waveguide deflector

IT Liquid crystals

(electrooptical waveguide deflectors employing)

IT Adsorbed substances

(Langmuir-Blodgett **monolayers**, electrooptical waveguide deflectors employing)

IT Waveguides

(electrooptical, deflectors)

IT Recording apparatus

(optical heads, pick-up, electrooptical waveguide deflectors for)

IT 1120-28-1, Methyl arachidate 9011-15-8, Poly(isobutyl methacrylate)

14923-81-0, Cadmium arachidate 25189-00-8, Poly(tert-butyl methacrylate)

141432-19-1 149306-57-0

RL: USES (Uses)

(electrooptical waveguide deflectors employing Langmuir-Blodgett films containing)

IT 84136-28-7, ZLI-1289

RL: USES (Uses)

(electrooptical waveguide deflectors employing liquid-crystal overlay cells containing)

IT 506-30-9, Arachidic acid

RL: RCT (Reactant); RACT (Reactant or reagent)

(reaction of, in Langmuir-Blodgett film preparation for electrooptical waveguide deflectors)

L8 ANSWER 10 OF 15 CAPLUS COPYRIGHT 2004 ACS on STN

141432-19-1 149306-57-0

RL: USES (Uses)

(electrooptical waveguide deflectors employing Langmuir-Blodgett films containing)

IT 84136-28-7, ZLI-1289

RL: USES (Uses)

(electrooptical waveguide deflectors employing liquid-crystal overlay cells containing)

IT 506-30-9, Arachidic acid

RL: RCT (Reactant); RACT (Reactant or reagent)

(reaction of, in Langmuir-Blodgett film preparation for electrooptical waveguide deflectors)

L8 ANSWER 10 OF 15 CAPLUS COPYRIGHT 2004 ACS on STN

AN 1988:194677 CAPLUS

DN 108:194677

ED Entered STN: 28 May 1988

TI Electrochemical noise at **passive** iron

AU Nachstedt, K.; Heusler, K. E.

CS Inst. Metallkd. Metallphys., Tech. Univ. Clausthal, Clausthal-Zellerfeld,
D-3392, Fed. Rep. Ger.

SO Electrochimica Acta (1988), 33(3), 311-21

CODEN: ELCAAV; ISSN: 0013-4686

DT Journal

LA English

CC 72-6 (Electrochemistry)

Section cross-reference(s): 55

AB With the described apparatus it was possible to measure (under potentiostatic conditions at frequencies .ltorsim.1 kHz) spectral densities of current noise comparable to the thermal noise at resistances of the order 1 MΩ. The spectral densities of the current noise at **passive** Fe microelectrodes in neutral borate or acetate buffer solns. were nearly frequency-independent at frequencies <10 Hz and increased with the square of the frequency at higher frequencies. The results are described by a nearly frequency-independent **voltage** noise source of intensity .apprx.1 order of magnitude larger than the thermal noise at the **electrode** impedance. The spectral densities of the current noise and the corresponding root-mean-square (rms) noise currents decreased with time during the approach to the steady state, with **electrode** potential due to the changes of the **electrode** impedance, and with **electrode** area. The current noise was increased by small heat flows through the **electrode**. At constant temperature, the noise was not affected by the exchange of electrolytes not containing ions causing pitting corrosion. The replacement of such inert electrolytes by electrolytes containing Cl⁻ resulted in an immediate increase of the spectral d. of the current noise and a subsequent decrease towards a steady state before the end of the incubation time. The rms noise current in the presence of Cl⁻, normalized to the noise current in absence of Cl⁻, was independent of **electrode** potential and proportional to the logarithm of the ratio between the actual Cl⁻ concentration and the critical

Cl⁻ concentration below which pitting never occurs. The **voltage** noise source became frequency-dependent with a maximum at .apprx.5 Hz. After onset of pitting, the low frequency noise of the 1/fa-type grew by several orders of magnitude. The results are explained in terms of local fluctuations of the thickness of the **passivating** film due to local adsorption of Cl⁻ followed by currentless dissoln. of oxide **monolayers** and subsequent growth or further dissoln. of the oxide film at random sites.

ST noise electrochem **passive** iron; current noise **passive** iron; chloride effect noise **passive** iron; pitting corrosion iron; acetate buffer electrochem noise iron; borate buffer electrochem noise iron

IT **Passivity**

(of iron, electrochem. noise in acetate or borate buffered solns. with and without chloride in relation to)

IT Electric noise

(electrochem., at **passive** iron in acetate or borate buffered solution, chloride effect on)

IT 16887-00-6, Chloride, properties

RL: PRP (Properties)

(current noise for **passive** iron in presence of)

IT 64-19-7, Acetic acid, properties 127-09-3, Sodium acetate 11129-12-7, Borate

RL: PRP (Properties)

AN 1988:194677 CAPLUS

DN 108:194677

ED Entered STN: 28 May 1988

TI Electrochemical noise at **passive** iron

AU Nachstedt, K.; Heusler, K. E.

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DT Journal

LA English

CC 72-6 (Electrochemistry)

Section cross-reference(s): 55

AB With the described apparatus it was possible to measure (under potentiostatic conditions at frequencies .1 to .1 kHz) spectral densities of current noise comparable to the thermal noise at resistances of the order 1 MΩ. The spectral densities of the current noise at **passive** Fe microelectrodes in neutral borate or acetate buffer solns. were nearly frequency-independent at frequencies <10 Hz and increased with the square of the frequency at higher frequencies. The results are described by a nearly frequency-independent **voltage** noise source of intensity .apprx. 1 order of magnitude larger than the thermal noise at the **electrode** impedance. The spectral densities of the current noise and the corresponding root-mean-square (rms) noise currents decreased with time during the approach to the steady state, with **electrode** potential due to the changes of the **electrode** impedance, and with **electrode** area. The current noise was increased by small heat flows through the **electrode**. At constant temperature, the noise was not affected by the exchange of electrolytes not containing ions causing pitting corrosion. The replacement of such inert electrolytes by electrolytes containing Cl⁻ resulted in an immediate increase of the spectral d. of the current noise and a subsequent decrease towards a steady state before the end of the incubation time. The rms noise current in the presence of Cl⁻, normalized to the noise current in absence of Cl⁻, was independent of **electrode** potential and proportional to the logarithm of the ratio between the actual Cl⁻ concentration and the critical

Cl- concentration below which pitting never occurs. The **voltage** noise source became frequency-dependent with a maximum at .apprx. 5 Hz. After onset of pitting, the low frequency noise of the 1/f-type grew by several orders of magnitude. The results are explained in terms of local fluctuations of the thickness of the **passivating** film due to local adsorption of Cl⁻ followed by currentless dissoln. of oxide **monolayers** and subsequent growth or further dissoln. of the oxide film at random sites.

ST noise electrochem **passive** iron; current noise **passive** iron; chloride effect noise **passive** iron; pitting corrosion iron; acetate buffer electrochem noise iron; borate buffer electrochem noise iron

IT **Passivity**

(of iron, electrochem. noise in acetate or borate buffered solns. with and without chloride in relation to)

IT Electric noise

(electrochem., at **passive** iron in acetate or borate buffered solution, chloride effect on)

IT 16887-00-6, Chloride, properties

RL: PRP (Properties)

(current noise for **passive** iron in presence of)

IT 64-19-7, Acetic acid, properties 127-09-3, Sodium acetate 11129-12-7, Borate

RL: PRP (Properties)

(current noise for **passive** iron in solution containing, effect of chloride on)

IT 7439-89-6, Iron, uses and miscellaneous

RL: USES (Uses)

(electrochem. noise at **passive** microelectrodes of, in acetate or borate buffered solns., chloride effect on)

(current noise for **passive** iron in solution containing, effect of chloride on)

IT 7439-89-6, Iron, uses and miscellaneous

RL: USES (Uses)

(electrochem. noise at **passive** microelectrodes of, in acetate or borate buffered solns., chloride effect on)

05

AN 1994:446193 CAPLUS
 DN 121:46193
 ED Entered STN: 23 Jul 1994
 TI Electro-optic waveguide deflector using a nonlinear optic film or liquid-crystal overlay cell for use in an optical pickup head
 IN Revelli, Joseph F., Jr.; Penner, Thomas L.; Armstrong, Nancy J.; Robello, Douglas R.; Schildkraut, Jay S.
 PA Eastman Kodak Co., USA
 SO U.S., 23 pp.
 CODEN: USXXAM
 DT Patent
 LA English
 IC ICM G02B006-10
 NCL 385008000
 CC 73-11 (Optical, Electron, and Mass Spectroscopy and Other Related Properties)
 Section cross-reference(s): 74, 75

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	US 5291567	A	19940301	US 1992-916422	19920721
	JP 06222400	A2	19940812	JP 1993-179070	19930720
PRAI	US 1992-916422		19920721		

CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
US 5291567	ICM	G02B006-10
	NCL	385008000

AB Electrooptical waveguide deflectors, appropriate for use in optical pickup heads, use any film exhibiting high second order susceptibility such as nonlinear optic organic Langmuir-Blodgett films or nonlinear optic organic poled

polymer films, or a liquid-crystal overlay cell. The deflector comprises a base support, a planar **electrode** layer disposed on the base support, a first buffer layer atop the first **electrode** layer, and an optical waveguide layer overlying the first buffer layer and planar **electrode**. When nonlinear optic films are used to form the waveguide layer, a second buffer layer is disposed atop the waveguide layer, and a pair of spaced **electrodes** is disposed atop the second buffer layer. When a nematic-type liquid-crystal overlay cell is used, it is disposed atop a **passive** dielec. waveguide, and a pair of spaced **electrodes** is disposed on the under surface of the liquid-crystal cell cover plate. The spaced **electrodes** are shaped so that selectively applying an elec. field causes deflection to vary with the applied **voltage** according to the geometrical configuration of the spaced **electrodes**. Methods for fabricating the deflectors are also described.

ST nonlinear optical film electrooptical waveguide deflector; liq crystal overlay cell waveguide deflector; Langmuir Blodgett film electrooptical waveguide deflector

IT Liquid crystals

(electrooptical waveguide deflectors employing)

IT Adsorbed substances

(Langmuir-Blodgett **monolayers**, electrooptical waveguide deflectors employing)

IT Waveguides

(electrooptical, deflectors)

IT Recording apparatus

(optical heads, pick-up, electrooptical waveguide deflectors for)

IT 1120-28-1, Methyl arachidate 9011-15-8, Poly(isobutyl methacrylate)

14923-81-0, Cadmium arachidate 25189-00-8, Poly(tert-butyl methacrylate)

AN 1966:16664 CAPLUS

DN 64:16664

OREF 64:3012b-c

ED Entered STN: 22 Apr 2001

TI Oxidation of hydrogen on nickel **electrodes** in sodium hydroxide solution

AU O'Brien, R. N.; Rao, K. V. N.

CS Univ. Alberta, Edmonton, Can.

SO Journal of the Electrochemical Society (1965), 112(12), 1245-8
CODEN: JESQAN; ISSN: 0013-4651

DT Journal

LA English

CC 15 (Electrochemistry)

AB Anodic polarization measurements are used to elucidate the mechanism of electrochem. oxidation of H on Ni **electrodes** in NaOH.

Potentiostatic expts. gave current-voltage curves for Ni

electrodes in 0.1, 0.5, and 1.0N NaOH which were Ni(OH)₂**passivation** curves. These curves had a peak current that

increased with NaOH concentration Coverage of the order of 1 or 2

monolayers of hydroxide suffices to reach **passivation**.

This decreased the rate of H oxidation with increasing potential because of

the decrease in the availability of surface uncovered by oxide. The

polarization is slightly lower in a solution stirred with H than in a solution

stirred with He because of the participation of dissolved H in the

electrode reaction.

IT Oxidation

(electrochem. or electrolytic, of H on Ni **electrodes** in NaOH)IT **Electrodes**

(nickel, H oxidation at, in NaOH)

IT **Passivation**

(of nickel, H oxidation and)

IT Polarization (electrolytic)

(of nickel, in H oxidation in NaOH)

IT 7440-02-0, Nickel

(electrodes, H oxidation at, in NaOH)

IT 1310-73-2, Sodium hydroxide

(hydrogen oxidation on Ni **electrodes** in solns. containing)

IT 1333-74-0, Hydrogen

(oxidation of, on Ni **electrodes** in NaOH)

AN 1990:412571 CAPLUS
DN 113:12571
ED Entered STN: 06 Jul 1990
TI Electrochemical properties of **covalently** bonded silane
amphiphile **monolayers** on a tin dioxide electrode
AU Okahata, Yoshio; Yokobori, Masatoshi; Ebara, Yasuhito; Ebato, Hiroshi;
Ariga, Katsuhiko
CS Dep. Polym. Chem., Tokyo Inst. Technol., Tokyo, 152, Japan
SO Langmuir (1990), 6(6), 1148-53
CODEN: LANGD5; ISSN: 0743-7463
DT Journal
LA English
CC 66-4 (Surface Chemistry and Colloids)
Section cross-reference(s): 72
AB A **monolayer** of atriethoxysilane amphiphile having 2 18-carbon
alkyl chains (2C18Si) was polymerized to form a Si-O-Si linkage on an acidic
water subphase, transferred onto a SnO2 electrode by a Langmuir-Blodgett
(LB) technique, and then **covalently** immobilized with Si-O-Sn
linkages on the electrode. The polymerized and **covalently**
immobilized 2C18Si **monolayer** was much more stable on the
electrode in harsh aqueous conditions than were noncovalently bonded
monolayers. The 2C18Si **monolayer** impeded the oxidation of
Fe(CN)64- as seen in the ratio of peak currents at the **monolayer**
-covered and uncovered electrodes ($i_p/i_{p0} = 0.2$). The reactivity could be
controlled reversibly by the phase transition from solid to liquid crystalline
state of the **monolayer**. The value $i_p/i_{p0} = 0.2$ indicates that
the 2C18Si **monolayer** on the SnO2 electrode cannot completely
block the penetration of ferrocyanide ions and still contains pinhole
defects in the **monolayer**, probably because the SnO2 electrode
has the hydrophilic and rough surface of metal oxides. These defects can
be eliminated completely by adsorbing a small amount of a long-chain alc.
(C14OH to C18OH) into the **monolayer** but not by adsorbing
branched bulky alcs. or short-chain alcs. (C6OH to C10OH).
ST adsorbed silane amphiphile tin dioxide electrode; electrochem property
silane amphiphile **monolayer**; ferrocyanide oxidn tin dioxide
electrode; **passivation** tin dioxide electrode surface
IT Adsorption
(of fatty alcs., on silane amphiphile **monolayers** immobilized
on tin dioxide electrode surface)
IT Oxidation, electrochemical
(of ferrocyanide, on tin dioxide electrodes coated with silane
amphiphile **monolayers**)
IT Surface energy
(of silane amphiphile **monolayers**, immobilized on tin dioxide
electrode)
IT Adsorbed substances
(silane amphiphile **monolayers**, immobilization of, on tin
dioxide electrode surface)
IT Alcohols, properties
RL: PEP (Physical, engineering or chemical process); PROC (Process)
(fatty, adsorption of, on silane amphiphile **monolayers**
immobilized on tin dioxide electrode)
IT 57-11-4, Stearic acid, uses and miscellaneous
RL: USES (Uses)
(adsorbed **monolayers** on tin dioxide electrode, electrochem.
properties in relation to)
IT 6865-35-6, Barium stearate 37519-63-4
RL: PRP (Properties)
(adsorbed **monolayers** on tin dioxide electrode, electrochem.
properties in relation to)
IT 105442-22-6 121231-18-3 121231-20-7

RL: PRP (Properties)

(adsorbed **monolayers**, immobilization of, on tin dioxide electrode)

IT 111-27-3, Hexyl alcohol, properties 111-87-5, Octyl alcohol, properties
112-30-1, Decyl alcohol 112-53-8, Dodecyl alcohol 112-72-1, Tetradecyl
alcohol 112-92-5, Octadecyl alcohol 36653-82-4, Hexadecyl alcohol

RL: PEP (Physical, engineering or chemical process); PROC (Process)
(adsorption of, on silane amphiphile **monolayers** immobilized
on tin dioxide electrode)

IT 18282-10-5, Tin oxide (SnO₂)

RL: PRP (Properties)

(electrochem. properties of adsorbed **monolayers** on electrode
containing)

IT 121231-18-3D, reaction products with tin dioxide

RL: PRP (Properties)

(surface, electrode properties in relation to)

AN 1990:412571 CAPLUS

DN 113:12571

ED Entered STN: 06 Jul 1990

TI Electrochemical properties of **covalently** bonded silane
amphiphile **monolayers** on a tin dioxide electrodeAU Okahata, Yoshio; Yokobori, Masatoshi; Ebara, Yasuhito; Ebato, Hiroshi;
Ariga, Katsuhiko

CS Dep. Polym. Chem., Tokyo Inst. Technol., Tokyo, 152, Japan

SO Langmuir (1990), 6(6), 1148-53

CODEN: LANGD5; ISSN: 0743-7463

DT Journal

LA English

CC 66-4 (Surface Chemistry and Colloids)

Section cross-reference(s): 72

AB A **monolayer** of atriethoxysilane amphiphile having 2 18-carbon alkyl chains (2C18Si) was polymerized to form a Si-O-Si linkage on an acidic water subphase, transferred onto a SnO₂ electrode by a Langmuir-Blodgett (LB) technique, and then **covalently** immobilized with Si-O-Sn linkages on the electrode. The polymerized and **covalently** immobilized 2C18Si **monolayer** was much more stable on the electrode in harsh aqueous conditions than were noncovalently bonded **monolayers**. The 2C18Si **monolayer** impeded the oxidation of Fe(CN)₆⁴⁻ as seen in the ratio of peak currents at the **monolayer**-covered and uncovered electrodes ($i_p/i_{p0} = 0.2$). The reactivity could be controlled reversibly by the phase transition from solid to liquid crystalline state of the **monolayer**. The value $i_p/i_{p0} = 0.2$ indicates that the 2C18Si **monolayer** on the SnO₂ electrode cannot completely block the penetration of ferrocyanide ions and still contains pinhole defects in the **monolayer**, probably because the SnO₂ electrode has the hydrophilic and rough surface of metal oxides. These defects can be eliminated completely by adsorbing a small amount of a long-chain alc. (C14OH to C18OH) into the **monolayer** but not by adsorbing branched bulky alcs. or short-chain alcs. (C6OH to C10OH).

ST adsorbed silane amphiphile tin dioxide electrode; electrochem property
silane amphiphile **monolayer**; ferrocyanide oxidn tin dioxide
electrode; **passivation** tin dioxide electrode surface

IT Adsorption

(of fatty alcs., on silane amphiphile **monolayers** immobilized
on tin dioxide electrode surface)

IT Oxidation, electrochemical

(of ferrocyanide, on tin dioxide electrodes coated with silane
amphiphile **monolayers**)

IT Surface energy

(of silane amphiphile **monolayers**, immobilized on tin dioxide
electrode)

IT Adsorbed substances

(silane amphiphile **monolayers**, immobilization of, on tin
dioxide electrode surface)

IT Alcohols, properties

RL: PEP (Physical, engineering or chemical process); PROC (Process)
(fatty, adsorption of, on silane amphiphile **monolayers**
immobilized on tin dioxide electrode)

IT 57-11-4, Stearic acid, uses and miscellaneous

RL: USES (Uses)

(adsorbed **monolayers** on tin dioxide electrode, electrochem.
properties in relation to)

IT 6865-35-6, Barium stearate 37519-63-4

RL: PRP (Properties)

(adsorbed **monolayers** on tin dioxide electrode, electrochem.
properties in relation to)

IT 105442-22-6 121231-18-3 121231-20-7

RL: PRP (Properties)

(adsorbed **monolayers**, immobilization of, on tin dioxide electrode)

IT 111-27-3, Hexyl alcohol, properties 111-87-5, Octyl alcohol, properties
112-30-1, Decyl alcohol 112-53-8, Dodecyl alcohol 112-72-1, Tetradecyl
alcohol 112-92-5, Octadecyl alcohol 36653-82-4, Hexadecyl alcohol

RL: PEP (Physical, engineering or chemical process); PROC (Process)
(adsorption of, on silane amphiphile **monolayers** immobilized
on tin dioxide electrode)

IT 18282-10-5, Tin oxide (SnO₂)

RL: PRP (Properties)

(electrochem. properties of adsorbed **monolayers** on electrode
containing)

IT 121231-18-3D, reaction products with tin dioxide

RL: PRP (Properties)

(surface, electrode properties in relation to)